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Date of Deposit: January 19, 2006

Case No. 9905/37
Client No. BIF116044/US

UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)	
)	
MORICEAU et al.)	
)	Examiner:
Serial No.: Not Yet Assigned)	Not Yet Assigned
)	
Filing Date: Herewith)	Group Art Unit:
)	Not Yet Assigned
For: STACKED STRUCTURE AND)	
PRODUCTION METHOD THEREOF)	

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Dear Sir:

In accordance with the duty of disclosure under 37 C.F.R. §1.56 and §§1.97-1.98, and more particularly in accordance with 37 C.F.R. §1.97(b), Applicants hereby cite the following references:

No.	Date of Publication	Patentee/Applicant/Country
US 2002/0145489 A1	10/10/2002	Cornett et al.
6,198,159 B1	03/06/2001	Hosoma et al.
5,259,247	11/09/1993	Bantien
FR 2 797 347 A1	02/09/2001	France
FR 2 736934 A1	01/24/1997	France
FR 2 681 472 A1	03/19/1993	France
FR 2 558 263 A1	07/19/1985	France
EP 0 754 953 B1	06/20/2001	EPO

Alley et al., "Surface Roughness Modification of Interfacial Contacts in Polysilicon Microstructures", Proceedings of the 7 th International Conference on Solid-State Sensors and Actuators, "Transducers '93," pp. 288-291, June 7-10, 1993, PACIFICO, Yokohama, Japan.
Aspar et al., "The Generic Nature of the Smart-Cut [®] Process for Thin-film Transfer", Journal of Electronic Materials, Vol. 30, No. 7, pp. 834-840, 2001.
Diem et al., "SOI 'SIMOX'; from bulk to surface micromachining, a new age for silicon sensors and actuators", Sensors and Actuators, Vol. A 46 - 47, pp. 8-16, 1995.
Goesele et al., "Semiconductor Wafer Bonding", Science and Technology, ECS Series, New Jersey 1999, <i>Annual Review of Material Science</i> , Vol. 28, pp. 215-241, 1998.
Liu et al., "Investigation of Interface in Silicon-on-Insulator by Fractal Analysis," <i>Applied Surface Science</i> , 187, pp. 187-191, 2002.
Schnell et al., "Plasma Surface Texturization for Multicrystalline Silicon Solar Cells", IEEE, XXVIII th Photovoltaic Conference, pp. 367-370, 2000.
Mastrangelo, C.H., "Suppression of Stiction in MEMS", Proceedings of the Materials Research Society Seminar, Vol. 605, pp. 1-12, 2000.
Yee et al., "Polysilicon Surface-Modification Technique to Reduce Sticking of Microstructures," <i>Sensors and Actuators A</i> 52, pp. 145-150, 1996.

For the Examiner's convenience, Applicants are enclosing Form PTO-1449 (two sheets) and copies of the requisite references. Applicants respectfully request the Examiner's consideration of the above references and entry thereof into the record of this application.

In accordance with 37 C.F.R. §1.98(a)(3), the applicants state the following: FR 2 797 347 A1 discloses a method for transferring a thin film of a source film to a target substrate. A non-certified English translation of the Abstract is enclosed herewith.

FR 2 681 472 A1 discloses a method for preparing thin films of semiconductor material. A non-certified English translation of the Abstract is enclosed herewith.

FR 2 558 263 A1 discloses a method for manufacturing a directional accelerometer. A non-certified English translation of the Abstract is enclosed herewith.

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FR 2 736934 A1 discloses a method for separating a structure with an effective layer. A non-certified English translation of the Abstract is enclosed herewith.

EP 0 754 953 B1 discloses a method for detaching a functional layer. A non-certified English translation of the Abstract is enclosed herewith.

Also enclosed is a copy of the International Search Report issued on December 28, 2004 for corresponding PCT Application No. PCT/FR04/001858 of the above-identified application.

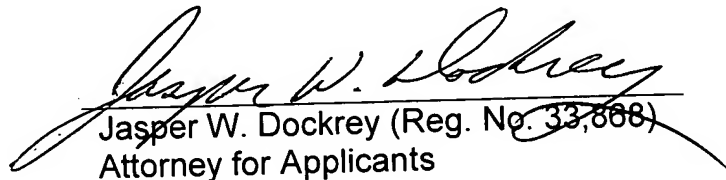
Applicants respectfully request the Examiner's consideration of the above references and entry thereof into the record of this application.

By submitting this Statement, Applicants are attempting to fully comply with the duty of candor and good faith mandated by 37 C.F.R. §1.56. As such, this Statement is not intended to constitute an admission that any of the enclosed references, or other information referred to therein, constitutes "prior art" or is otherwise "material to patentability," as that phrase is defined in 37 C.F.R. §1.56(a).

Applicants have calculated no fee to be due in connection with the filing of this Statement. However, the Director is authorized to charge any fee deficiency associated with the filing of this Statement to a deposit account, as authorized in the Transmittal accompanying this Statement.

Respectfully submitted,

January 19, 2006


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FORM PTO-1449	SERIAL NO. Not Yet Assigned	CASE NO. 10/565,621 05/37 2BIF 11, 44/US
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT	FILING DATE Herewith	GROUP ART UNIT Not Yet Assigned
APPLICANTS: MORICEAU et al.		

REFERENCE DESIGNATION U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER <small>Number-Kind Code (if known)</small>	DATE	NAME	CLASS/ SUBCLASS	FILING DATE
	A1	US 2002/0145489 A1	10/10/2002	Cornett et al.		
	A2	6,198,159 B1	03/06/2001	Hosoma et al.		
	A3	5,259,247	11/09/1993	Bantien		

FOREIGN PATENT DOCUMENT

EXAMINER INITIAL		DOCUMENT NUMBER <small>Number-Kind Code (if known)</small>	DATE	COUNTRY	CLASS/ SUBCLASS	TRANSLATION YES OR NO
	A4	FR 2 797 347 A1	02/09/2001	France		Abstract only
	A5	FR 2 736934 A1	01/24/1997	France		Abstract only
	A6	FR 2 681 472 A1	03/19/1993	France		Abstract only
	A7	FR 2 558 263 A1	07/19/1985	France		Abstract only
	A8	EP 0 754 953 B1	06/20/2001	EPO		Abstract only

EXAMINER INITIAL	OTHER ART – NON PATENT LITERATURE DOCUMENTS <small>(Include name of author, title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date page(s), volume-issue number(s), publisher, city and/or country where published.</small>	
	A9	Alley et al., "Surface Roughness Modification of Interfacial Contacts in Polysilicon Microstructures", Proceedings of the 7 th International Conference on Solid-State Sensors and Actuators, "Transducers '93," pp. 288-291, June 7-10, 1993, PACIFICO, Yokohama, Japan.
	A10	Aspar et al., "The Generic Nature of the Smart-Cut [®] Process for Thin-film Transfer", Journal of Electronic Materials, Vol. 30, No. 7, pp. 834-840, 2001.
	A11	Diem et al., "SOI 'SIMOX'; from bulk to surface micromachining, a new age for silicon sensors and actuators", Sensors and Actuators, Vol. A 46 - 47, pp. 8-16, 1995.
	A12	Goesele et al., "Semiconductor Wafer Bonding", Science and Technology, ECS Series, New Jersey 1999, <i>Annual Review of Material Science</i> , Vol. 28, pp. 215-241, 1998.

EXAMINER	DATE CONSIDERED
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

FORM PTO-1449	SERIAL NO. Not Yet Assigned	CASE NO. 10/565621 9505/37 (BIF116044/US)
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT (use several sheets if necessary)	FILING DATE Herewith	GROUP ART UNIT Not Yet Assigned
APPLICANTS: MORICEAU et al.		

EXAMINER INITIAL	OTHER ART – NON PATENT LITERATURE DOCUMENTS (Include name of author, title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date page(s), volume-issue number(s), publisher, city and/or country where published.	
	A13	Liu et al., "Investigation of Interface in Silicon-on-Insulator by Fractal Analysis," <i>Applied Surface Science</i> , 187, pp. 187-191, 2002.
	A14	Schnell et al., "Plasma Surface Texturization for Multicrystalline Silicon Solar Cells", IEEE, XXVIII th Photovoltaic Conference, pp. 367-370, 2000.
	A15	Mastrangelo, C.H., "Suppression of Stiction in MEMS", Proceedings of the Materials Research Society Seminar, Vol. 605, pp. 1-12, 2000.
	A16	Yee et al., "Polysilicon Surface-Modification Technique to Reduce Sticking of Microstructures," <i>Sensors and Actuators A</i> 52, pp. 145-150, 1996.

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